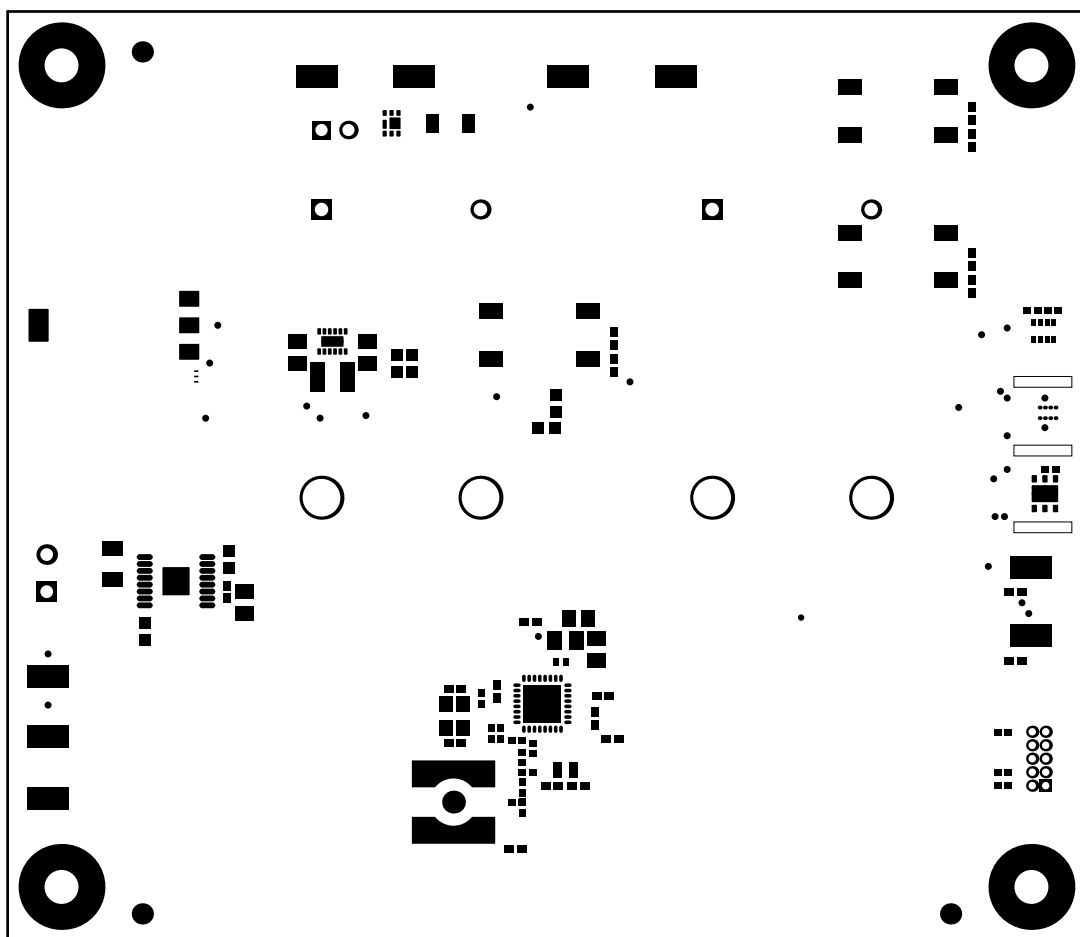
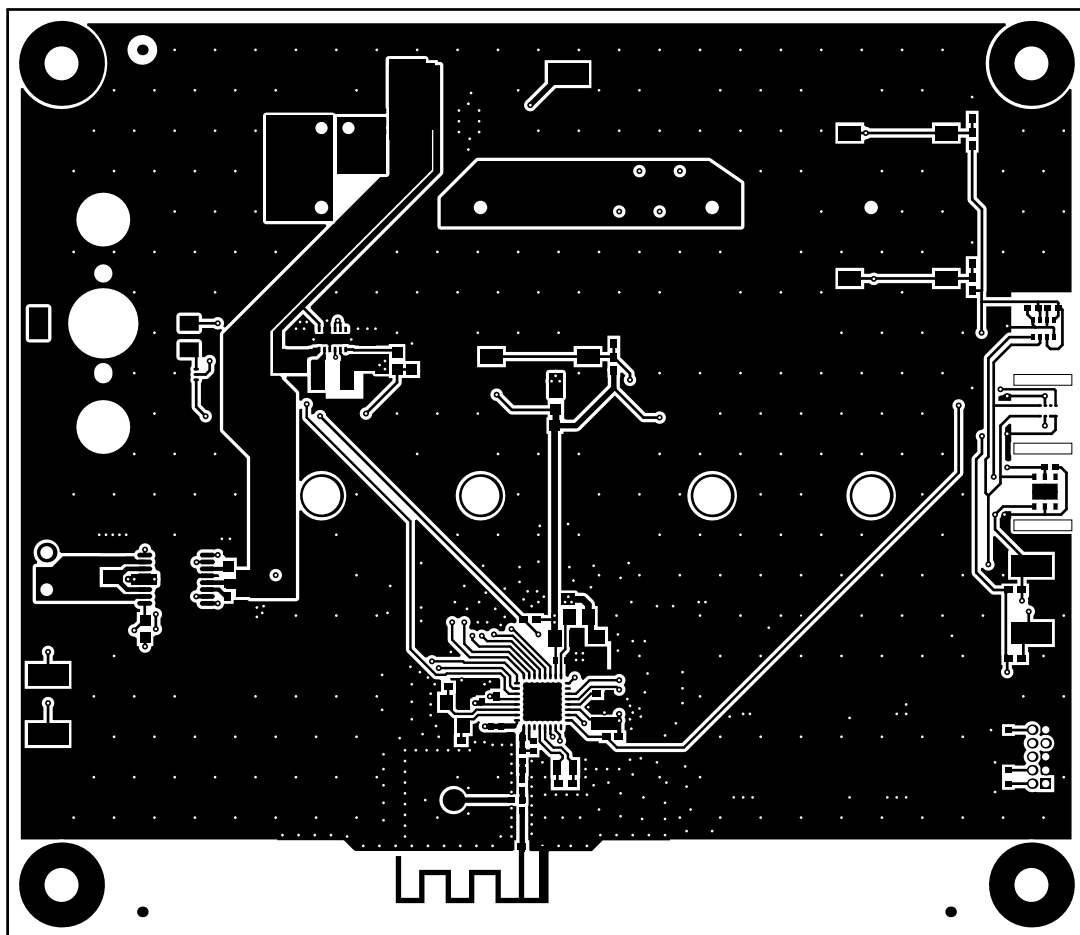


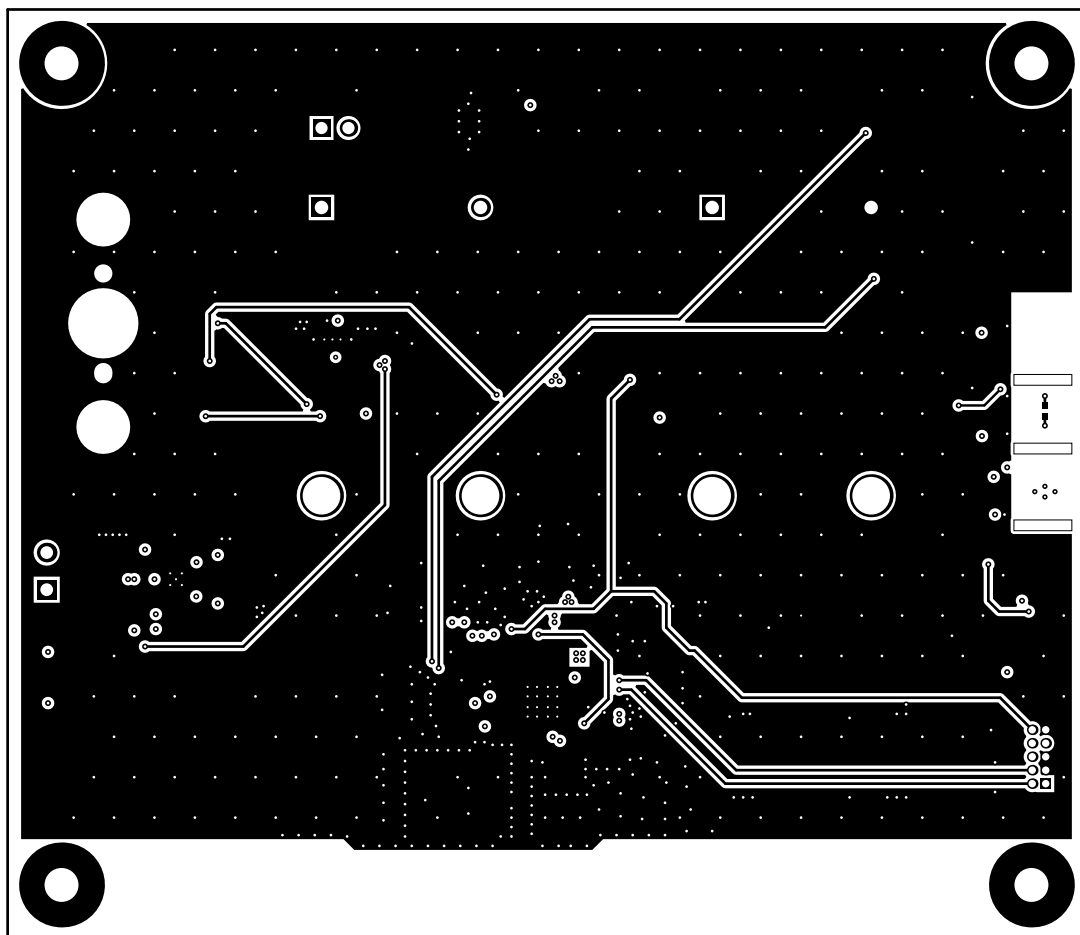
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01067	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: 01067		
PLOT NAME = Top Overlay	GENERATED : 6/19/2017	9:55:59 AM	TEXAS INSTRUMENTS



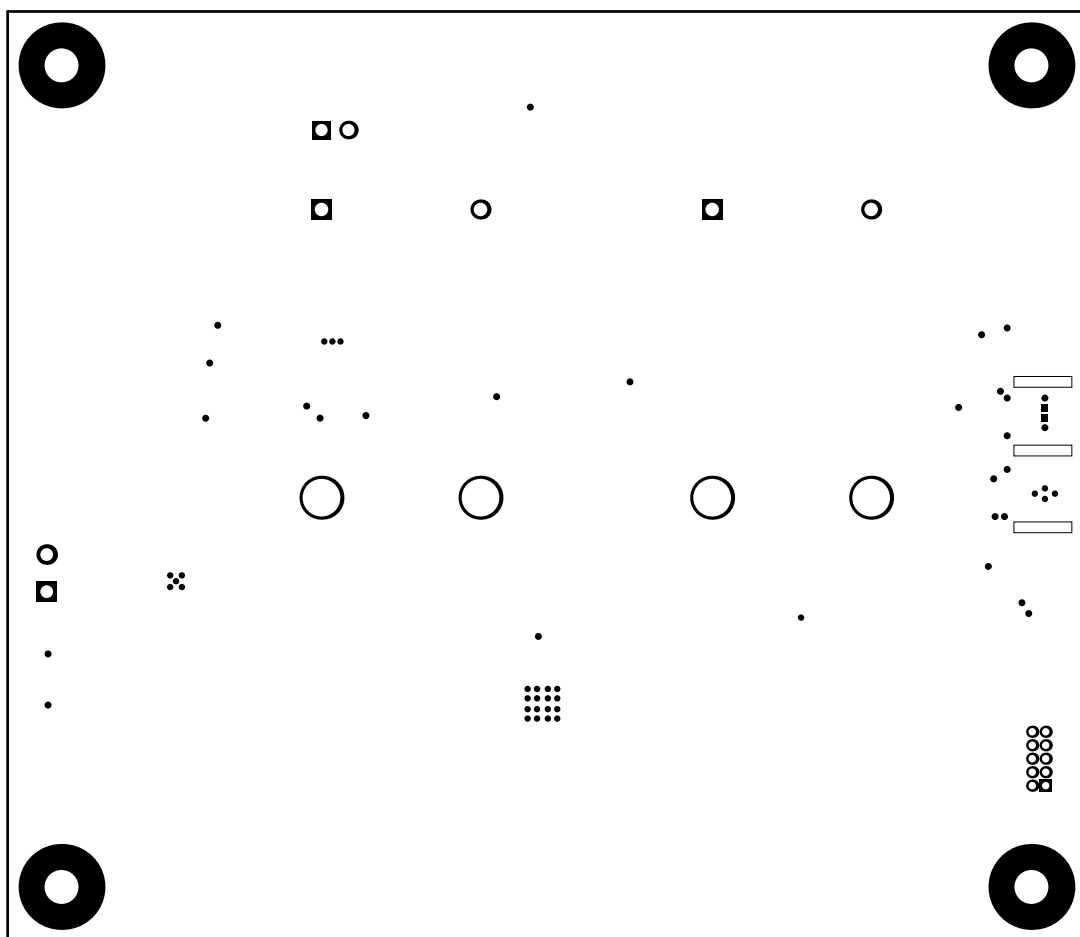
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01067	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: 01067		
PLOT NAME = Top Solder Mask	GENERATED : 6/19/2017 9:56:01 AM	TEXAS INSTRUMENTS	



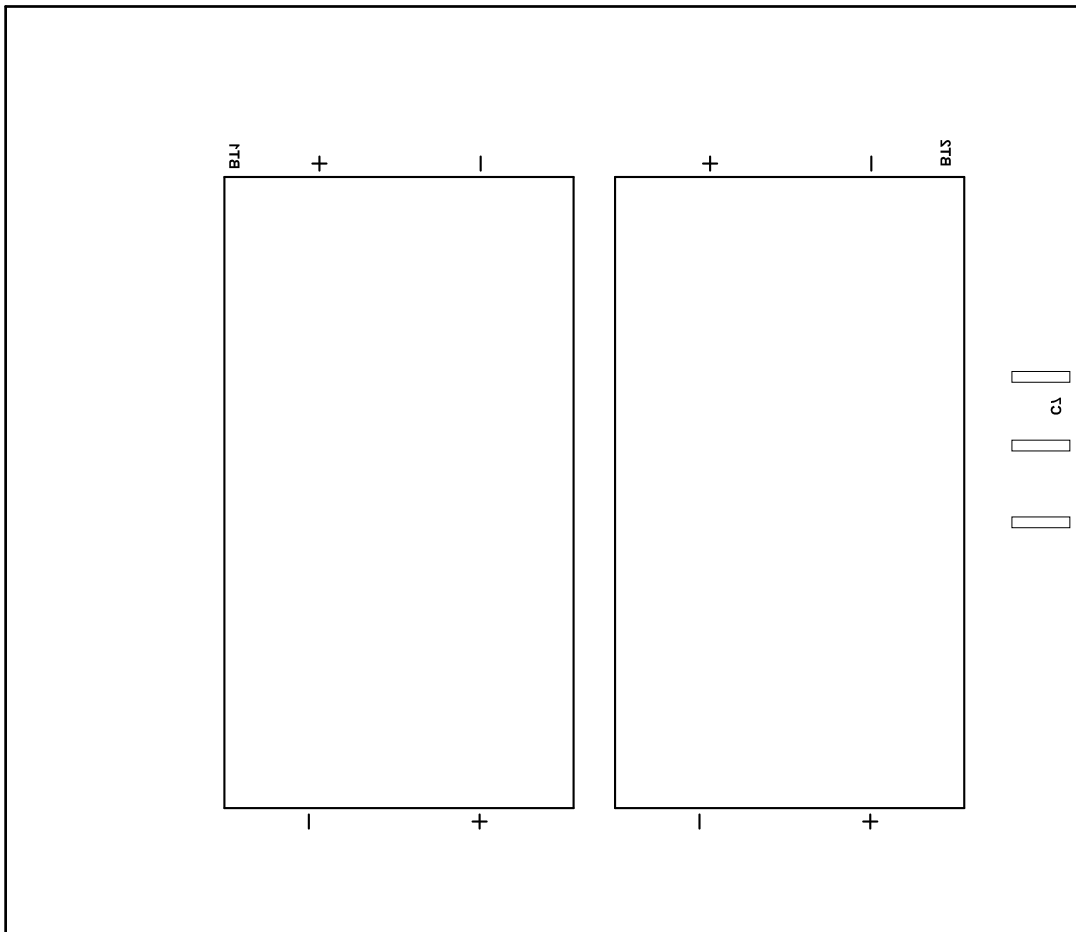
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01067	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: 01067		
PLOT NAME = Top Layer	GENERATED : 6/19/2017 9:56:02 AM	TEXAS INSTRUMENTS	



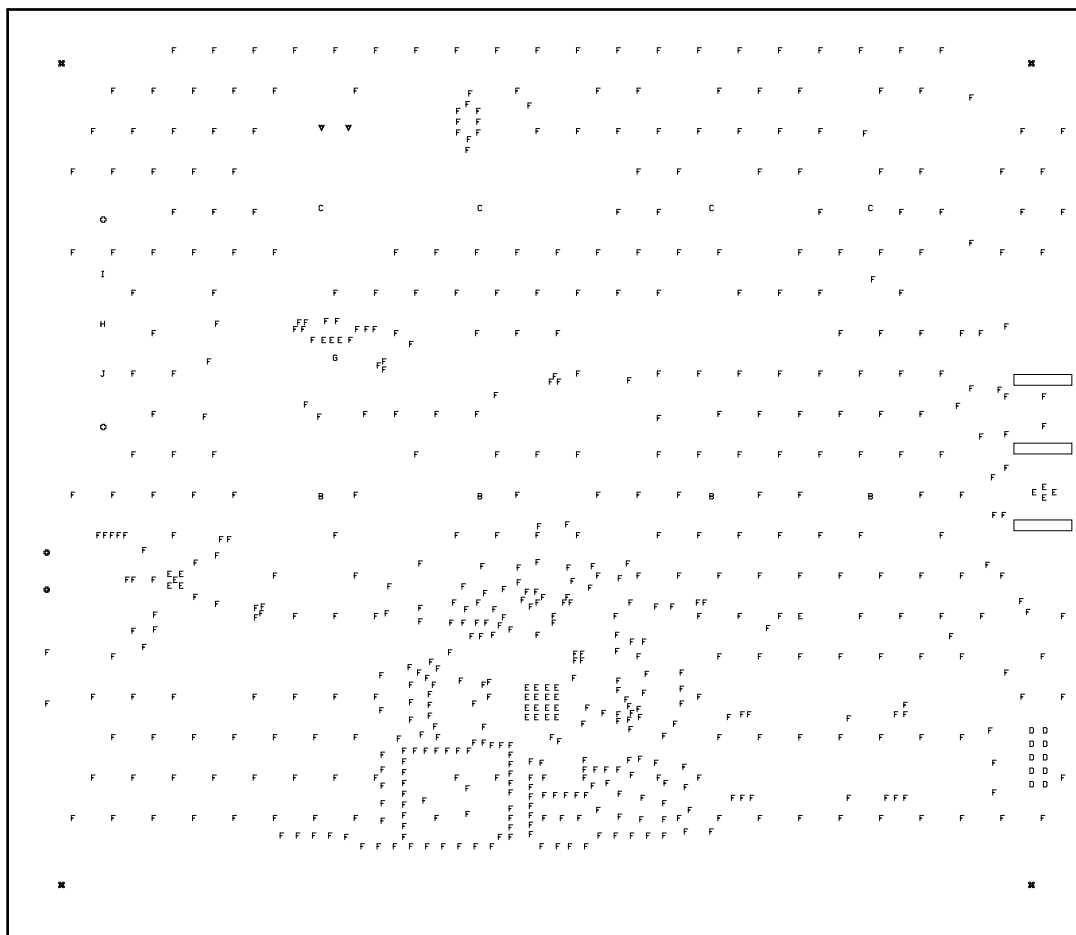
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01067	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: 01067		
PLOT NAME = Bottom Layer	GENERATED : 6/19/2017 9:56:03 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01067	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: 01067		
PLOT NAME = Bottom Solder Mask	GENERATED : 6/19/2017 9:56:05 AM	TEXAS INSTRUMENTS	



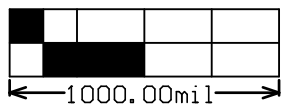
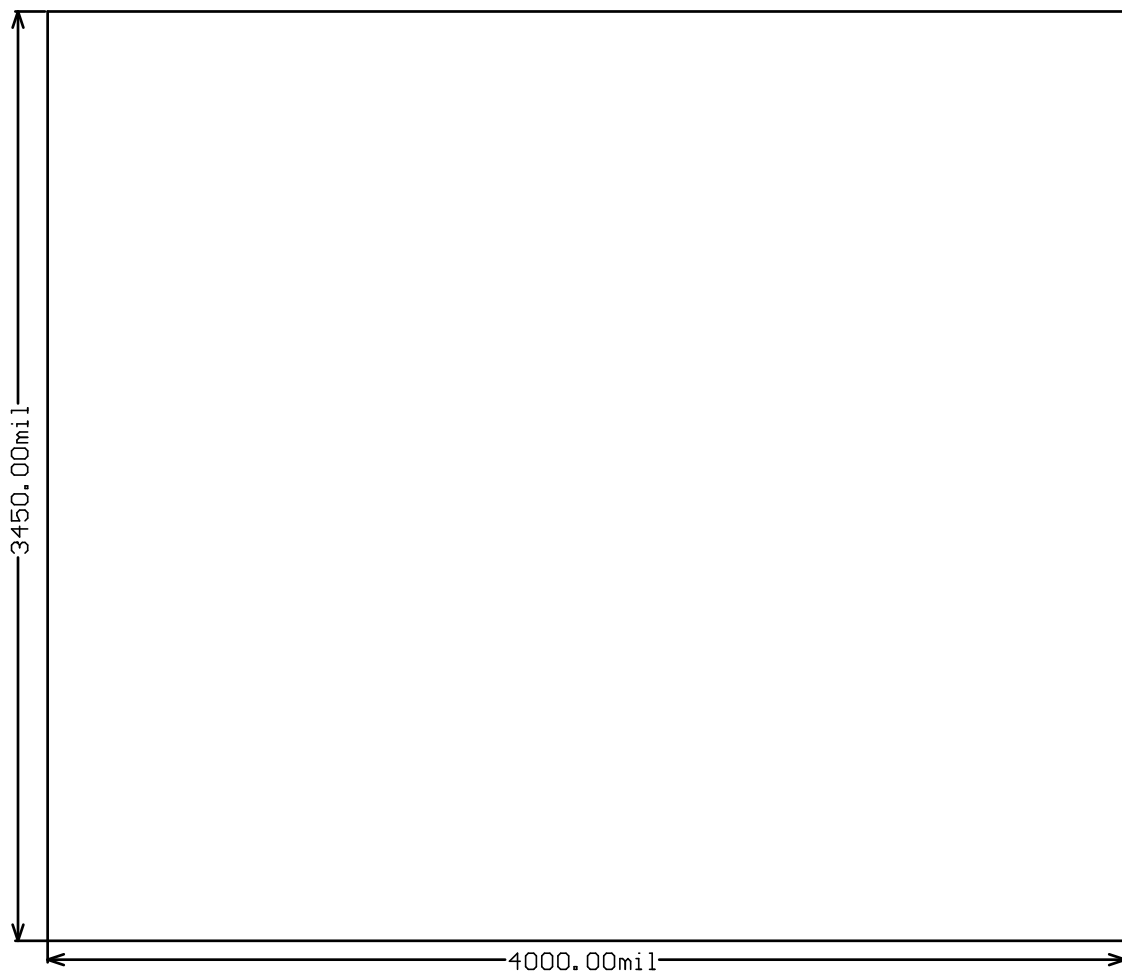
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01067	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: 01067		
PLOT NAME = Bottom Overlay	GENERATED : 6/19/2017 9:56:06 AM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Tolerance
I	1	43.31mil (1.100mm)	NPTH	Round	Top Layer - Bottom Layer	
⊙	2	175.00mil (4.445mm)	NPTH	Round	Top Layer - Bottom Layer	
H	1	236.22mil (6.000mm)	NPTH	Round	Top Layer - Bottom Layer	
E	29	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
G	1	8.00mil (0.203mm)	PTH	Round	Top Layer - Bottom Layer	
F	587	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	
D	10	27.56mil (0.700mm)	PTH	Round	Top Layer - Bottom Layer	
▽	2	45.28mil (1.150mm)	PTH	Round	Top Layer - Bottom Layer	
⊕	2	47.24mil (1.200mm)	PTH	Round	Top Layer - Bottom Layer	
C	4	50.00mil (1.270mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	4	125.98mil (3.200mm)	PTH	Round	Top Layer - Bottom Layer	
B	4	139.76mil (3.550mm)	PTH	Round	Top Layer - Bottom Layer	
J	1	43.31mil (1.100mm)	NPTH	Slot	Top Layer - Bottom Layer	
648 Total						

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01067	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: 01067		
PLOT NAME = Drill Drawing	GENERATED : 6/19/2017 9:56:07 AM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01067	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: 01067		
PLOT NAME = Board Dimensions	GENERATED : 6/19/2017 9:56:10 AM	TEXAS INSTRUMENTS	

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